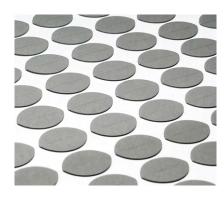
THER NCs-800-17-50 Patron



Non-Silicone Thermal Conductive Pad



Non-Silicone Thermal Compound NCs-800 is made of non-silicon resin material. No low molecular siloxane volatilization and low total volatile gas, no electrical contact & pollution problems. NCs-800 is flexible and has great thermal conduction, Low com-pressive stress and high com-pressive characteristics can effectively reduce the stress load of components, so that the equipment only needs to bear less mechanical stress, and at the same time, it can have low thermal resistance and high thermal conductivity.

FEATURES

- / Thermal conductivity: 17.0 W/m*K / It's made by non-silicone resin materials
- / Low contact thermal resistance
- / With electrical insulation
- / Outstanding thermal conductivity / Applicable to optical and sensitive

electric components

TYPICAL APPLICATION

/ HDDS

- / Optical appliance
- / 5G base station & infrastructure
- / EV electric vehicle

HOW TO ORDER

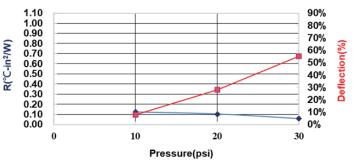
Patron THER NÔs-Ì €€-FÏ -Í 0 XXX-YYY-ZZmm XXX = width in mm YYY = depth in mm ZZ = thickness in mm

TYPICAL PROPERTIES

PROPERTY	NCs-800	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.3	ASTM D792	g/cm³
Hardness	50	ASTM D2240	Shore OO
Tensile Strength	0.15	ASTM D412	Kgf/cm ²
Application temperature	-60~125	-	°C
Low molecular Siloxane (D3 to D20 total)	N.D	Gas Chromatography	%
Outgassing CVCM (wt%)	0.0043	-	-
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	8	ASTM D5470 modify	%
Deflection @20 psi	28	ASTM D5470 modify	%
Deflection @30 psi	55	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	>1011	ASTM D257	Ohm
Volume resistivity	>1010	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	17.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.122	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.103	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.058	ASTM D5470	°C-in²/ W

The chemical formula indicates that if Cyclic polydimethylsilox-ane (HO-[Si(CH3)2O]n-H) is non-reaction, it's volatile anytime and everywhere. For example, when the electric products which has been put in a confined space, the volatile of low-molecular-weight silox-anes will makes the elecetic products uncontacted.

Thermal Resistance vs. Pressure vs. Deflection



https://www.patron-components.com/